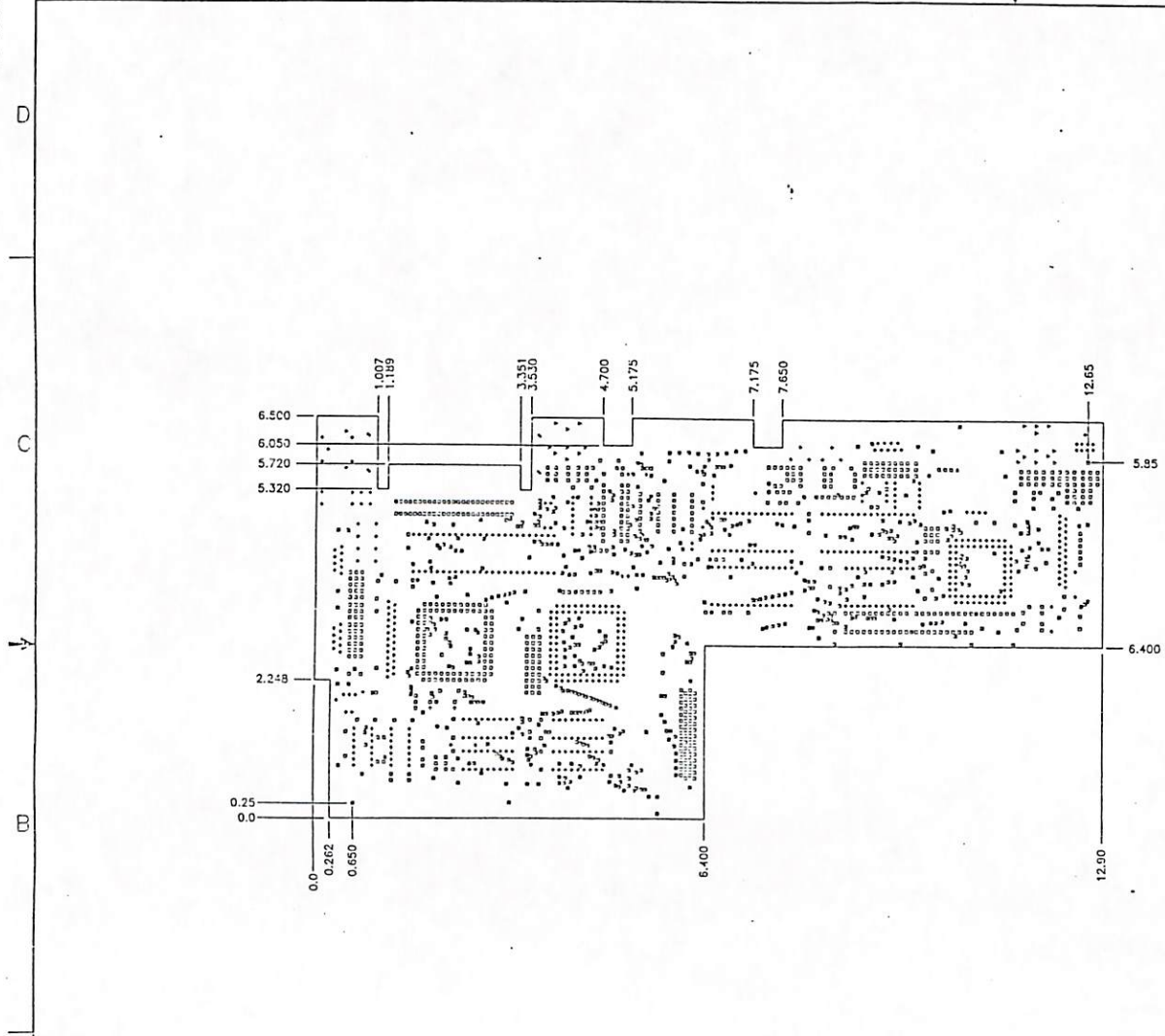


8 7 6 5 4 3 2 1

REVISIONS				
NO.	REV.	DESCRIPTION	DATE	APPROVED
1		PILOT PRODUCTION RELEASE	1-2-91	<i>[Signature]</i>



NOTES: (UNLESS OTHERWISE SPECIFIED)

- BOARDS SHALL BE FABRICATED IN ACCORDANCE WITH THE BEST COMMERCIAL PRACTICES. FABRICATE PER COMMODORE SPEC. NO. 1.01.007.
- MATERIAL:
 - BASE LAMINATE, COPPER GLAD, GLASS BASE, EPOXY RESIN, (FR4 GRADE OR EQUIVALENT) 1 OZ. COPPER ON EXTERNAL LAYERS, PER MIL-P-13949.
 - THICKNESS AND ACCUMULATION OF INDIVIDUAL LAYER TOLERANCES SHALL BE OPTIMIZED TO ACHIEVE AN OVERALL THICKNESS OF 1.57 (0.062)
 - BONDING AGENT, PREIMPREGNATED B-STAGE EPOXY GLASS CLOTH SHALL BE IN ACCORDANCE WITH MIL-G-55636.
- PLATING EXTERNAL LAYERS AND THRU HOLES:
 - THE HOLE WALLS SHALL BE PREPARED FOR PLATING BY SENSITIZING WITH ELECTROLESS COPPER PROVIDING THE CONDUCTIVE BASE FOR SUBSEQUENT PLATING.
 - ELECTRO-DEPOSITED COPPER SHALL BE IN ACCORDANCE WITH MIL-C-14550, CLASS 1, 0.002 (0.001) MINIMUM THICKNESS.
 - SOLDER PLATE TO BE 60 / TIN, 40 / LEAD, ±10 / AND SHALL BE AN AVERAGE MINIMUM THICKNESS OF 0.0051 (0.0002) WITH NO SINGLE MEASUREMENT LESS THAN 0.0025 (0.0001) AFTER REFLOW.
 - COPPER DEPOSITED ON SURFACE CONDUCTORS SHALL BE A MINIMUM THICKNESS OF 0.001 (0.0024).
 - SOLDER PLATING SHALL COVER ALL EXPOSED COPPER ON TRACES AND PADS, WITH A MINIMUM THICKNESS OF 0.051 (0.002) AFTER REFLOW.
 - THE PLATING SHALL BE HOMOGENEOUS AND COMPLETELY COVER CONDUCTORS WITHOUT PITS, PINHOLES, OR OTHER NON-UNIFORMITIES.
 - ANNULAR RINGS SHALL BE COMPLETE AND UNBROKEN SURROUNDING EACH ROUND TERMINAL PAD BY A MINIMUM OF 0.050 (0.002).
- CONDUCTOR AREA:
 - LOW STRESS NICKEL PLATING SHALL BE A MINIMUM OF 0.0076 (0.0003) AND 0.025 (0.001) MAX. IN ACCORDANCE CC-N-290 CLASS II, TYPE IV.
 - GOLD PLATING SHALL BE A MINIMUM OF 0.0076 (0.00003) AND SHALL BE IN ACCORDANCE WITH MIL-C-45240, TYPE II, GRADE C, CLASS 1.
- HOLES WHOSE LOCATIONS ARE NOT DIMENSIONED ARE TO BE CENTERED ON THE PAD AREA WITHIN 0.178 (0.007) OF THE CENTER OF THE PAD.
- FRONT TO BACK REGISTRATION SHALL BE WITHIN 0.127 (0.005)
- ALL DIMENSIONS ARE IN MILLIMETERS (INCHES).
- ALL TOOLING HOLE DIAMETERS ARE TO HAVE A TOLERANCE OF +0.080 (+0.003), -0.000 (-0.000).
- ARTWORK PROVIDED PER COMMODORE SPEC. NO. 1.01.007 SECT. 4.2
- THIS FAB. DWG. IS USED WITH ARTWORK NO. 313368-01.
- SILKSCREEN COMPONENT SIDE USING ARTWORK SUPPLIED.
- SOLDERMASK BOTH SIDES PER IPS-SM813.
- HOLES INDICATED AS BEING ON GRID SHALL BE CENTERED WITHIN 0.076 (0.003) OF THEIR TRUE POSITION POINT, REF. BY X-Y DATA.
- BOARDS SHALL BE IDENTIFIED WITH THE VENDORS U.L. REGISTERED LOGO ON THE COMPONENT SIDE.
- PC BOARD LAYER:
 - LAYER 1 ----- COMPONENT SIDE
 - LAYER 2 ----- SOLDER SIDE

SYMBOL	HOLE DIAMETER	QUANTITY
□	0.037	655
△	0.043	1
▽	0.052	21
⊠	0.100	5
⊡	0.125	13
◇	0.042	569
⊙	0.062	8
⊚	0.073	7
⊛	0.084	7
⊜	0.093	4
⊝	0.018	579

C.A.D. GENERATED

DATE: 1/23/91

DESIGNED BY: N. SIKOTI

DATE: 1/23/91

DRWING NO: 313368-01

SCALE: 1:1

SIZE: 313367

REV: 1

SHEET 1 OF 1

Commodore FABRICATION DRAWING, C65

8 7 6 5 4 3 2 1